

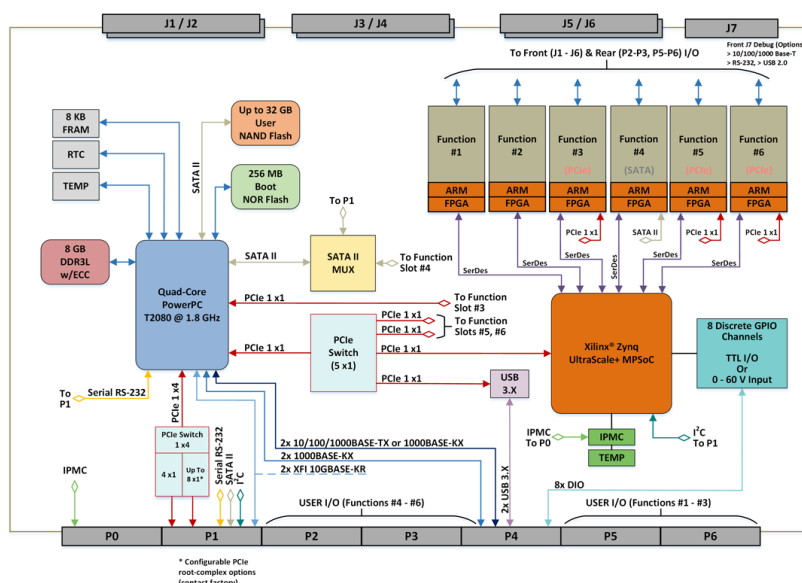


67PPC2 6U OpenVPX Single Board Computers

6U OpenVPX Single Board Computer (SBC)

Six I/O and communication function module slots for over 100 different modules to choose from

The 67PPC2 is a 6U OpenVPX NXP® PowerPC based Single Board Computer that can be configured with up to six NAI smart I/O and communication function modules. Ideally suited for rugged Mil-Aero applications, the 67PPC2 delivers off-the-shelf solutions that accelerate deployment of SWaP-optimized systems in air, land and sea applications.



Features

- Slot profile: SLT6-PAY-2F2U2T-10.2.5**
Module profile: MOD6- PAY-2F2U2T-12.2.5-3
 - Data plane: 1 x4 & 4 x1 PCIe
 - Control plane: 2x 10/100/1000Base-T or 2X 1000Base-KX
- NXP QorIQ® T2080 Quad Core e6500 Processor @ 1.8 GHZ**
 - 8 GB DDR SDRAM
 - 32 GB SATA II NAND Flash
- 1x USB 2.0, to front maintenance J7**
- 2x USB 3.0, to rear I/O**
- I²C bus to rear I/O (option)**
- 1x RS232 console (development) port, to front J7 and rear I/O**
- Supports six NAI smart I/O function modules**
 - COSA® architecture
 - 100+ modules to choose from
 - Independent x1 SerDes interface to each function module slot
 - PCIe interface to function slot #3, 5, 6 (e.g. for additional Gig-E ports option)
 - SATA II interface to function slot #4 (e.g. for 480 GB expansion function option)
- Front and/or rear I/O**
- 8x Discrete Input (60 V) to rear I/O (option)**
- External SATA II interface (option)**
- IPMC Support (configured option)**
 - VITA 46.11 Tier-2 compatible
- Wind River® VxWorks®, DDC-I Deos™ OS or Linux® BSP/OS Support**
- Intelligent I/O library support included**
- Continuous Background BIT**
- VICTORY Interface Services (Contact factory)**
- 25 W MB power dissipation**
- Designed to meet systems level:**
 - Operating temperature:
 - Commercial: 0°C to 70°C
 - Rugged: -40°C to 85°C
 - MIL-STD-461 (EMI)
 - MIL-STD-810 (vibration/shock)

Select up to 6 independent functions for your application

I/O Modules					
Function	Module	Description	Function	Module	Description
Analog-to-Digital	<u>AD1</u>	12 CH. A/D, ± 10 V, Dedicated, 256 kHz (max), Sigma-Delta	Digital IO - Differential Transceiver	<u>DF1</u>	16 CH. Differential I/O, Input: -10 V to +10 V (422), -7 V to +12 V (485) Output: -25 V to +5 V
	<u>AD2</u>	12 CH. A/D, ± 100 V (max), Dedicated, 256 kHz (max), Sigma-Delta		<u>DF2</u>	16 CH. 16 Channel Enhanced Differential I/O
	<u>AD3</u>	12 CH. A/D, ± 25 mA, Dedicated, 256 kHz (max), Sigma-Delta	Discrete IO - Multichannel, Programmable	<u>DT1</u>	24 CH. Discrete I/O, 0-60 VDC Input/Output, Max Iout 500 mA - 2 A, Source/Sink (out)
	<u>AD4</u>	16 CH. A/D, ± 10 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		<u>DT2</u>	16 CH. Discrete I/O, ± 80 V Input/Output, Max Iout 600 mA, Isolated/Ch Switch (out)
	<u>AD5</u>	16 CH. A/D, ± 50 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		<u>DT3</u>	4 CH. Discrete Hi & Lo Side Switch Output @ 65V/2A (max), external individual supplied VCC & VSS per channel pair
	<u>AD6</u>	16 CH. A/D, ± 100 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		<u>DT4</u>	24 CH. Enhanced DT1
	<u>ADE</u>	16 CH. A/D, ± 10 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		<u>DT5</u>	16 CH. Enhanced DT2
	<u>ADF</u>	16 CH. A/D, ± 100 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling	Relay	<u>RY1</u>	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Non Latching
Chip Detector and Fuzz Burn	<u>CD1</u>	6 CH. Chip Detector (CD) and Fuzz Burn (FB)		<u>RY2</u>	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Latching
Digital-to-Analog	<u>DA1</u>	12 CH. D/A, ± 10 V, 25 mA Per Channel, Current or Voltage Control	Digital IO - TTL, CMOS	<u>TL1</u>	24 CH. TTL I/O, Standard Functionality, Programmable
	<u>DA2</u>	16 CH. D/A, ± 10 V, 10 mA Per Channel, No Current Control		<u>TL2</u>	24 CH. TTL I/O, Enhanced Functionality, Programmable
	<u>DA3</u>	4 CH. D/A, ± 40 V, ± 100 mA, Voltage or Current Output	Variable Reluctance	<u>VR1</u>	8 CH. Variable Reluctance Signal Input and General-Purpose Pulse Counter, ± 100 V, 100 kHz (max)
	<u>DA4</u>	4 CH. D/A, ± 20 to ± 80 , 10 mA, Voltage Control Only			
Measurement & Simulation Modules					
Function	Module	Description	Function	Module	Description
AC Reference	<u>AC2</u>	2 CH. AC Reference Source, 47 Hz - 20 KHz, $\pm 3\%$ Acc, 2 - 28 Vrms, 6 VA (Max/Ch) Power	LVDT RVDT Measurement and Simulation	<u>LD5</u>	4 CH. LVDT/RVDT to Digital, 28-90 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 KHz Freq
	<u>AC3</u>	2 CH. AC Reference Source, 47 Hz - 2.5 KHz, $\pm 3\%$ Acc, 28 - 115 Vrms, 6 VA (Max/Ch) Power	Synchro Resolver Measurement and Simulation	<u>DSx</u> (<u>DRx</u>)	1 - 3 CH. Digital to Synchro/Resolver, 2 - 90 VLL, 2 - 1115 Vrms Exc, 47 Hz - 20 kHz Freq
LVDT RVDT Measurement and Simulation	<u>DLx</u>	1 - 3 CH. Digital to LVDT/RVDT, 2 - 90 Vrms Full Scale, 2 - 115 Vrms Exc, 47 Hz - 20 kHz Freq		<u>SDx</u>	4 CH. Synchro/Resolver to Digital, 2 - 90 Vrms Input, 2 - 115 Vrms Exc, 47 Hz to 20 kHz Freq
	<u>LD1</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 KHz Freq	Thermocouple and RTD Measurement	<u>RT1</u>	8 CH. Resistance Temperature Detectors (RTD), 2, 3, or 4 wire, 16 Bit Res, 16.7 Hz/Ch
	<u>LD2</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 1 KHz - 5 KHz Freq		<u>TC1</u>	8 CH. Thermocouple, 4.17 - 470 Hz, ± 100 mV A/D
	<u>LD3</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 5 KHz - 10 KHz Freq		<u>TR1</u>	8 CH. Thermocouple (TCx) & Resistance Temperature Detectors (RTD), programmable per channel
	<u>LD4</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 10 KHz - 20 KHz Freq	Strain Gauge Measurement	<u>SG1</u>	4 CH. Strain Gauge, 4.7 Hz - 4.8 KHz, Measurement, Conventional 4-Arm Bridge

Communication Modules					
Function	Module	Description	Function	Module	Description
ARINC Communications	<u>AR1</u>	12 CH. ARINC 429, 100 KHz or 12.5 KHz, RX/TX, 256 Word Tx/Rx Buffer	MIL-STD-1553B	<u>FTE</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled
	<u>AR2</u>	1 CH. ARINC 568 (CH-1, RX & TX) & 1 Channel ARINC 579 (CH-2, Programmable RX or TX), 1024-Word TX & RX Buffers per Ch.		<u>FTF</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled
CANBus Communications	<u>CB1</u>	8 CH. CANBus, CAN 2.0 A/B, 16 K RX/TX Buffer, 1 Mb/s Max Data Rate	MIL-STD-1760	<u>FTJ</u>	1 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled
	<u>CB2</u>	8 CH. CANBus, J1939, 16 K RX/TX Buffer, 500 kb/s Max Data Rate		<u>FTK</u>	2 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled
	<u>CB3</u>	8 CH. CANBus, CAN 2.0 A/B (CB1) or J1939 (CB2) protocol layer programmable per channel	IEEE 1394 (FireWire)	<u>FW1</u>	2 CH. (nodes), IEEE 1394b (Firewire), tri-port per channel, including TLIM
Ethernet NIC Interface	<u>EM1</u>	2 CH. Dual Ethernet I/F, Intel 82850, 10/100/1000		<u>FW2</u>	2 CH. (nodes), IEEE 1394b (Firewire), tri-port per channel, direct (no TLIM)
Ethernet Switch	<u>ES2</u>	16 CH. (Ports) (max.) Ethernet Switch, 10/100/1000Base-T (GbE), 4 x Fiber Optic Ports (opt.), Layer 2+/3 Managed	Serial Communications	<u>SC1</u>	4 CH. Serial, RS-232/422/423 (MIL-STD-188C)/485, Non Isolated
MIL-STD-1553B	<u>FTA</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled		<u>SC3</u>	8 CH. (max) RS-232/422/485 Serial Communications or GPIO, Programmable, Non-isolated
	<u>FTB</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		<u>SC5</u>	4 CH. RS-232/422/485 communications, isolated per channel and from SYS GND
	<u>FTC</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		<u>SC6</u>	4 CH. RS-232/422/485 communications, individual SYS GND provided per channel (non-isolated)
	<u>FTD</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Direct Coupled	Time-Triggered Ethernet	<u>TE2</u>	3 CH. Single Channel, Tri-Redundant TTE/A664p7/AFDX/Best Effort End System
Storage					
Function	Module	Description	Function	Module	Description
SATA Solid State Drive (SSD)	<u>FM2</u>	1 CH. 480 GB MLC SATA Flash, extended temp -40°C to 85°C operation	SATA Solid State Drive (SSD)	<u>FM9</u>	1 CH. 1.92 TB SATA TLC NAND Flash, Extended Temperature Operation
	<u>FM8</u>	1 CH. 1 TB SATA TLC NAND Flash, Extended Temperature Operation			
Combination Modules					
Function	Module	Description	Function	Module	Description
Combo	<u>CM5</u>	2 CH. Dual-redundant MIL-STD-1553 & 8 Channel ARINC 429/575, 100 KHz or 12.5 KHz, RX or TX, 256 Word Tx/Rx Buffer	Combo	<u>CM8</u>	2 CH. Dual-redundant MIL-STD-1553 & 12 Channel Discrete I/O, 0-60 VDC Input/Output, Max Iout 500 mA - 2 A, Source/Sink (out)

Architected for Versatility

NAI's Configurable Open Systems Architecture™ (COSA®) offers a choice of over 100 smart I/O, communications, or Ethernet switch functions, providing the highest packaging density and greatest flexibility of ruggedized embedded product solutions in the industry. Preexisting, fully-tested functions can be combined in an unlimited number of ways quickly and easily.

One-Source Efficiencies

Eliminate man-months of integration with a configured, field-proven system from NAI. Specification to deployment is a seamless experience as all design, state-of-the-art manufacturing, assembly and test are performed - by one trusted source. All facilities are located within the U.S. and optimized for high-mix/low volume production runs and extended lifecycle support.

Product Lifecycle Management

From design to production and beyond, NAI's product lifecycle management strategy ensures the long-term availability of COTS products through configuration management, technology refresh and obsolescence component purchase and storage.

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